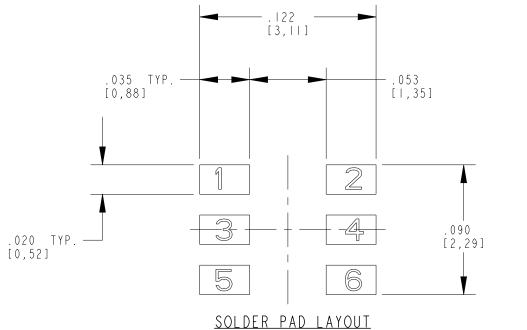
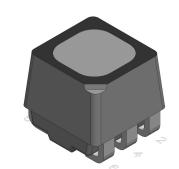
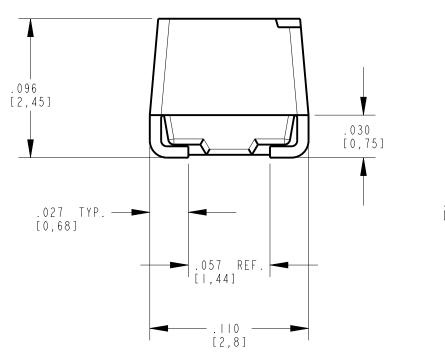
REV	REVISIONS	DRN	APP	DATE
Α	NEW RELEASE	JGL	NO	8/06/2020



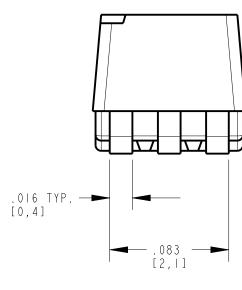


<u>001</u>	SCALE 10.000

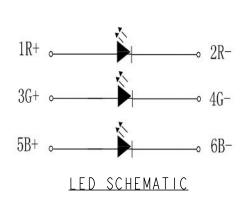


[2,8]

[2,7]



—PIN-MARK



ELECTRICAL & OPTICAL CHARACTERISTICS (Ts=25°C)						
ITEM	SYMBOL	CONDITION	R	G	В	UNITS
REVERSE CURRENT	I R	V <sub>R</sub> =5V	6	6	6	μΑ
	V <sub>F(min)</sub>	I <sub>F</sub> =20mA	1.7	2.7	2.7	V
FORWARD VOLTAGE	V <sub>F(avg)</sub>					V
	V <sub>F(max)</sub>		2.4	3.4	3.4	V
DOMINANT WAVELENGTH	λD	I <sub>F</sub> =20mA	618~628	518~530	464~474	nm
SPECTRUM RADIATION BANDWIDTH	Δλ	I <sub>F</sub> =20mA	2 4	38	30	nm
LUMINOUS INTENSITY	l <sub>V(min)</sub>	l <sub>=</sub> =20mA	520	1200	250	mc d
LUMINOUS INTENSTIT	l V (avg)	' -	680	1500	380	mc d
VIEWING ANGLE	201/2	I <sub>F</sub> =20mA		110		d e g

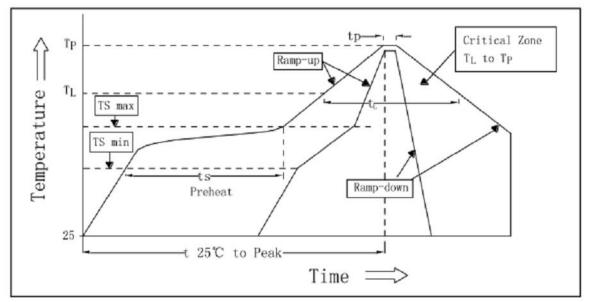
		DATINOS	, T 0 5 0 0 1		
	MAXIMUM RATINGS (Ts=25°C)				
ITEM	SYMBOL	ABSOLUT	HMITC		
I I [  V		R	G	В	UNITS
FORWARD CURRENT	I <sub>F</sub>	25	20	20	m A
PULSE FORWARD CURRENT	I <sub>FP</sub>	80	80	80	m A
REVERSE VOLTAGE	v <sub>R</sub>	5	5	5	V
OPERATING TEMPERATURE	T <sub>OPR</sub>		-30~+85		°C
STORAGE TEMPERATURE	T <sub>STG</sub>		-40~+100		°C
POWER DISSIPATION	PD	60	68	68	mW
ELECTROSTATIC DISCHARGE(HBM)	ESD	1000V			

- NOTES:
  I. PIN NUMBERS ARE FOR REFERENCE ONLY, DESIGNATION NON EXISTENT ON PART
- 2. LABELING FOR REEL AND OUTSIDE OF ALUMINUM BAG,
  DIALIGHT P/N QUANTITY PER REEL, DATE CODE, INTENSITY BIN CODE,
  LOT NUMBER AND COUNTRY OF ORIGIN.
- 3.STORAGE CONDITIONS FOR TAPED PRODUCTS: RE-TAPING MAY BE NECESSARY FOR PRODUCTS STORED MORE THAN 12 MONTHS.
- 4. DRY PACK PACKAGING CONSIST OF A DESICCANT, HUMIDITY INDICATOR CARD IN A VACUUM SEALED MOISTER BARRIERBAG, MOISTER SENSITIVITY LABEL LEVEL 5A ON OUTSIDE BAG.
- 5. QUATITY: 3,000 PIECES PER REEL/BAG.
- 6. HBM CLASS IB
- 7. OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC SENSITIVE DEVICES.
- 8. PART No: 598-8G10-313F



THIS DRAWING AND THE CONTENTS HEREIN ARE CONFIDENTIAL AND THE SOLE PROPERTY OF DIALIGHT CORP. REPRODUCTION OF THIS DRAWING OR CONSTRUCTION OF ANY PARTS WITHIN THIS DRAWING ARE FORBIDDEN WITHOUT THE WRITTEN CONSENT OF DIALIGHT CORP.						
	TERNAL REFERENCE ONLY = 3D MODEL : 4500521857323-A.3  DRAWING NUMBER	RFV				
SCALE: 15.000	DRAWING NUMBER	K E V				
ALL DIM'S IN: INCHES (MM)	C-18481	Δ				
TOLERANCES: UNLESS OTHERWISE SPECIFIED	C-10401	Λ.				
FRACTIONS: ±1/64 DECIMALS (.XX): ±.01	SM 2828 RGB W/6 LEADS					
DECIMALS (.XXX): ±.005 DECIMALS (.XXXX): ±.0005 ANGLES: ±1°	MATERIAL					
FINISH	DIGIONT FARMINGDAL (732)	E 34 SOUTH E, NJ 07727 919-3119 light.com				
FSCM 83330	SHEET I OF 2 FAMILY TABLE:					

## SMT REFLOW SOLDERING INSTRUCTIONS



AVERAGE TEMPERATURE RISE SPEED (Tsmax to Tp)	MAX 4°C/s
PREHEATING: MINIMUM TEMPERATURE (Tsmin)	150°C
PREHEATING: MAX. TEMPERATURE (Tsmax)	200°C
PREHEATING: TIME (Tsmin to Tsmax)	60s-120s
TIME LIMITED TO MAINTAIN HIGH TEMPERATURE: THE TEMPERATURE	2 I 7° C
TIME LIMITED TO MAINTAIN HIGH TEMPERATURE: THE TIME	MAX 60s
PEAK/CLASSIFICATION OF TEMPERATURE: (Tp)	250°C
SOLDERING TIME:	MAX 10s
RAMP-DOWN RATE:	6°C/s max

## SOLDERING NOTES:

- I. REFLOW SOLDERING SHOULD NOT BE DONE MORE THAN ONE TIMES.
- 2. IT IS RECOMMENDED THE USE OF MIDDLE TEMPERATURE SOLDER PASTE.
- 3. STRESS ON THE LEDS SHOULD BE AVOIDED DURING HEATING IN SOLDERING PROCESS.
- 4. AFTER SOLDERING, DO NOT DEAL WITH THE PRODUCT BEFORE TEMPERATURE IS DOWN TO ROOM TEMPERATURE.

## 13 INCH DIA. REEL SPECIFICATIONS

